

CLAIMS

1. A polyimide-metal laminated body obtained by forming a metal conductive layer on a polyimide film, which has been ceramic-modified or pseudoceramic-modified on at least the surface, by a wet plating process capable of accomplishing metal plating on ceramic.

2. A polyimide-metal laminated body according to claim 1, wherein the metal conductive layer comprises an electroless copper plating layer and an electrolytic copper plating layer thereover.

3. A polyimide-metal laminated body according to claim 1, which is further subjected to heat treatment at 100-350°C for 1 minute to 10 hours after or before the metal plating.

4. A polyimide-metal laminated body according to claim 1, wherein the initial peel strength of the metal layer of the metal conductive layer with respect to the polyimide film is at least 0.5 kg/cm in a 90° peel test, and is also at least 0.5 kg/cm even after aging treatment in 150°C air.

5. A polyimide-metal laminated body according to claim 1, wherein the wet plating process accomplishes electroless copper plating of a surface alumina-modified or silica-modified film, after forming on a ceramic an electroless metal oxide ground layer or electroless nickel ground layer which can be removed by etching treatment, and thereby allows the cohesion to be improved and oxidation of the copper and polyimide interface to be prevented, in order to avoid cohesive degradation during overheating.

6. A polyimide-metal laminated body according to claim 1, wherein the polyimide film has a thermal expansion coefficient of 5×10^{-6} to 25×10^{-6} cm/cm/°C (average of MD, TD) at 50-200°C.

7. A polyimide-metal laminated body obtained by forming a metal conductive layer on a polyimide film,

which has been ceramic-modified or pseudo-ceramic modified on at least the surface, by a wet plating process, wherein the initial peel strength with respect to the polyimide film is at least 0.5 kg/cm in a 90° peel test, and is also at least 0.5 kg/cm even after aging treatment in 150°C air for 1 week (168 hours).

8. A polyimide circuit board obtained by forming a circuit by a process which includes a step of forming a metal conductive layer on a polyimide film, which has been ceramic-modified or pseudo-ceramic modified on at least the surface, by a wet plating process capable of accomplishing metal plating on ceramic, wherein a photosensitive resist layer is formed before the metal plating process or during the metal plating process, and then the resist at the pattern-forming sections is removed by a photoprocess and a conductive metal layer plating is grown at the removed sections.